

Product / Package Information

Package	MSOP
Body Size/Pitch	
Lead Count	8
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A & B

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.11 E-02	87.3	873000	44.09	440923
Thermosets	Phenol Resin	Proprietary	5.72 E-04	4.5	45000	2.27	22728
Thermosets	Epoxy Resin 1	Proprietary	3.81 E-04	3.0	30000	1.52	15152
Thermosets	Epoxy Resin 2	Proprietary	3.81 E-04	3.0	30000	1.52	15152
Others	Others	Proprietary	2.54 E-04	2.0	20000	1.01	10101
Other inorganic materials	Carbon Black	1333-86-4	2.54 E-05	0.2	2000	0.10	1010
Subtotal			1.27 E-02	100.0	1000000	51	505067

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	9.75 E-03	97.5	975000	38.77	387709
Copper & its alloys	Iron	7439-89-6	2.35 E-04	2.35	23500	0.93	9345
Copper & its alloys	Zinc	7440-66-6	1.20 E-05	0.12	1200	0.05	477
Copper & its alloys	Phosphorus	7723-14-0	3.00 E-06	0.03	300	0.01	119
Subtotal			1.00 E-02	100	1000000	40	397650

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.01 E-04	100	1000000	0.40	4017

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.55 E-04	100	1000000	2.61	26057

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.10 E-04	99.99	1000000	1.23	12328

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.00 E-03	100	1000000	3.98	39769

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.06 E-04	80.50	805000	1.22	12165
Other organic materials	Carbocyclic Acrylates	Proprietary	3.80 E-05	10.00	100000	0.15	1511
Other organic materials	Bismaleimide resin	Proprietary	1.14 E-05	3.00	30000	0.05	453
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	1.14 E-05	3.0	30000	0.05	453
Others	Additive	Proprietary	1.14 E-05	3.0	30000	0.05	453
Other organic materials	Dicumyl peroxide	80-43-3	1.90 E-06	0.5	5000	0.008	76
Subtotal			3.80 E-04	100.00	1000000	1.51	15112

Package Totals			Weight (g)	2.51 E-02		Percentage (%)	100	PPM	1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability any inaccuracy of such information.



ADI Proprietary

Product / Package Information	
Package	MSOP - COL
Body Size/Pitch	
LeadCount	8
Option	NiPdAu

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliance	Level A Compliant

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.11 E-02	87.7	877000	45.48	454800
Thermosets	Epoxy Resin	Proprietary	6.35 E-04	5.0	50000	2.59	25929
Thermosets	Phenol Resin	Proprietary	6.35 E-04	5.0	50000	2.59	25929
Thermosets	Epoxy Cresol Novolac	29690-82-2	2.54 E-04	2.0	20000	1.04	10372
Other inorganic materials	Carbon Black	1333-86-3	3.81 E-05	0.3	3000	0.16	1556
Subtotal			1.27 E-02	100.0	1000000	52	518587

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	9.72 E-03	97.5	975000	39.70	397009
Copper & its alloys	Iron	7439-89-6	2.34 E-04	2.35	23500	0.96	9569
Copper & its alloys	Zinc	7440-66-6	1.20 E-05	0.12	1200	0.05	489
Copper & its alloys	Phosphorus	7723-14-0	2.99 E-06	0.03	300	0.01	122
Subtotal			9.97 E-03	100	1000000	41	407189

Internal/External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	1.16 E-04	90.91	909091	0.47	4743
Precious metals	Palladium	7440-05-3	1.01 E-05	7.91	79051	0.04	412
Precious metals	Gold	7440-57-5	1.52 E-06	1.19	11858	0.01	62
Subtotal			1.28 E-04	100.00	1000000	0.52	5217

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.10 E-04	99.99	1000000	1.27	12657

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.00 E-03	100	1000000	4.08	40834

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Aluminum oxide	Proprietary	1.33 E-04	35	350000	0.54	5431
Other organic materials	Diethylene glycol monoethyl ether acetate	Proprietary	1.33 E-04	35	350000	0.54	5431
Thermoset	Epoxy Resin	Proprietary	9.50 E-05	25	250000	0.39	3879
Others	Amine	Proprietary	1.90 E-05	5	50000	0.08	778
Subtotal			3.80 E-04	100	1000000	1.55	15517

Package Totals	Weight (g)	Percentage (%)	PPM
	2.45 E-02	100	1000000

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ADI Proprietary

Product / Package Information

Package	MSOP
Body Size	
Lead Count	8
Terminal Finish	SnPb

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
JIG Material Content Compliance	No

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.09 E-02	86.20	862000	43.46	434602
Thermosets	Epoxy resin	Proprietary	9.53 E-04	7.50	75000	3.78	37813
Thermosets	Phenol Novolac	9003-35-4	5.08 E-04	4.00	40000	2.02	20167
Other inorganic materials	Antimony Trioxide	1309-64-4	1.91 E-04	1.50	15000	0.76	7563
Thermosets	Brominated Resin	40039-93-8	6.35 E-05	0.50	5000	0.25	2521
Other inorganic materials	Carbon Black	1333-86-4	3.81 E-05	0.30	3000	0.15	1513
Subtotal			1.27 E-02	100	1000000	50.42	504179

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	9.76 E-03	97.57	975706	38.73	387289
Copper & its alloys	Iron	7439-89-6	2.28 E-04	2.28	22789	0.90	9046
Copper & its alloys	Zinc	7440-66-6	1.26 E-05	0.13	1263	0.05	501
Copper & its alloys	Phosphorus	7723-14-0	2.42 E-06	0.02	242	0.01	96
Subtotal			1.00 E-02	100.00	1000000	39.69	396932

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.01 E-04	100.0	1000000	0.40	4010

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.95 E-04	85.0	850000	2.36	23621
Tin & its alloys	Lead	7439-92-1	1.05 E-04	15.0	150000	0.42	4168
Subtotal			7.00 E-04	100.0	1000000	2.78	27789

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.10 E-04	99.99	1000000	1.23	12306

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.00 E-03	100.0	1000000	3.97	39699

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.04 E-04	80	800000	1.21	12069
Thermosets	Epoxy Resin	Proprietary	5.70 E-05	15	150000	0.23	2263
Others	Curing agent & hardener	Proprietary	1.90 E-05	5	50000	0.08	754
Subtotal			3.80 E-04	100	1000000	1.51	15086

Package Totals			Weight (g) 2.52 E-02			Percentage (%) 100.00	PPM 1000000
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